



## Final Product Change Notification

201904029F01

**Issue Date:** 16-May-2019

**Effective Date:** 14-Aug-2019

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For detailed information we invite you to view this notification online

**This notice is NXP Company Proprietary.**



# QUALITY

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

**20PDIP Assembly Site  
Transfer to TFME from ATP1**

### Description of Change

NXP Semiconductors announces the assembly site transfer for the MC9S08SH8&SH4 PDIP 20 package from the current Amkor Technology Philippines Inc (ATP1), Muntinlupa, Philippines assembly facility to TongFu Microelectronics Co., Ltd. Nantong China.

The change in assembly site also includes change in mold compound, Epoxy, wire metal and lead frame. ATP1 and TFME BOM comparison is attached to this notification.

Please see attached files for additional details.

### Reason for Change

The Amkor Technology Philippines (ATP1), Muntinlupa, Philippines assembly facility will not support PDIP20 package assembly and need to qualify TongFu Microelectronics Co., Ltd. as PDIP20 new assembly site.

### Identification of Affected Products

Top side marking

The assembly site is reflected in the package trace code.

The format for the NXP standard trace

PDIP20: AWLYYWWZ or ATWLYYWWZ

A=Assembly Location, WL=Wafer Lot, YYWW=Date Code, Z =Assembly Lot Split,

The marking for ATP1 is A=ZR

The marking for TFME is A=XN

### Product Availability

### Sample Information

Samples are available upon request  
PC9S08SH8MPJ can support custom sample, need 6 weeks build time.

#### **Production**

Planned first shipment 30-Aug-2019

#### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

No impact on form, fit, function, reliability or quality.

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 15-Jun-2019.

#### **Remarks**

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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#### **Affected Part Numbers**

MC9S08SH8CPJ

MC9S08SH4CPJ